ADDRESS AND DESCRIPTION OF THE OWNER OWNER OF THE OWNER O	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				er both This docur level parts	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21 1 1-				Form Type * Distribute						ials and Mfg Information				
Supplier Informati	on													
Company name*			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2024-09-20			
Contact Name			Title - Contact			Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Ite	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective	Date	ate Version Manufacturing Site		V	Veight*	UOM	Unit Type	
		NCP1096PAG Integrated PoE-PD integrated hot swap		nterface Controller with FET, IEEE 802.3bt, 90V	2024-09-2	20	BE4		6	4.0	mg	Each		
Manufacturing Pro	occess Information									_				
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	FD-020 MSL Rating Peak Process Body Temperature Max Time at Peak					Temperatu	ire Num	ber of Reflow Cyc	les		
Matte Tin (Sn) - annealed			CU Alloy 2		260	260 C 30		30	seconds 3					
Comments														
TTENTION: MSL 2 I	Rated item requires Dry	y Pack (af	ter electrical	test)										
or more information r	egarding material com	position p	lease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.3	mg	Supplier	Silicon (Si)	7440-21-3		5.3	mg
Die Attach	1.3	mg	Supplier	Silver (Ag)	7440-22-4		1.105	mg
			Supplier	Acrylic resins	Proprietary Data		0.195	mg
Die Attach Tape	1.3	mg	Supplier	Oxirane, (chloromethyl)-, homopolymer	24969-06-0		0.195	mg
			Supplier	2-Propenoic acid, 2-methyl-, polymer with butyl 2-propenoate and methyl 2-methyl-2-propenoate	25035-69-2		0.195	mg
			Supplier	Proprietary	Proprietary Data		0.13	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.585	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.195	mg
Lead Frame	32.6	mg	Supplier	Silver (Ag)	7440-22-4		0.0978	mg
			Supplier	Magnesium (Mg)	7439-95-4		0.0326	mg
			Supplier	Silicon (Si)	7440-21-3		0.2282	mg
			В	Nickel (Ni)	7440-02-0		0.978	mg
			Supplier	Copper (Cu)	7440-50-8		31.2634	mg
Mold Compound-Black	22.9			Epoxy resin	proprietary data		1.603	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0687	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.839	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.3893	mg
Plating	0.5	mg	Supplier	Tin (Sn)	7440-31-5		0.5	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg